

- Optimized for Off-Line and dc-to-dc Converters
- Low Start-Up Current (<1 mA)
- Automatic Feed-Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load-Response Characteristics
- Undervoltage Lockout With Hysteresis
- Double-Pulse Suppression
- High-Current Totem-Pole Output
- Internally Trimmed Bandgap Reference
- 500-kHz Operation
- Error Amplifier With Low Output Resistance
- Designed to Be Interchangeable With UC2842 and UC3842 Series

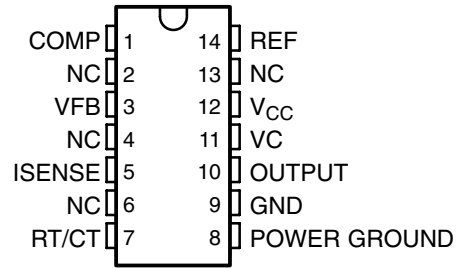
description/ordering information

The TL284x and TL384x series of control integrated circuits provide the features that are necessary to implement off-line or dc-to-dc fixed-frequency current-mode control schemes, with a minimum number of external components. Some of the internally implemented circuits are an undervoltage lockout (UVLO), featuring a start-up current of less than 1 mA, and a precision reference trimmed for accuracy at the error amplifier input. Other internal circuits include logic to ensure latched operation, a pulse-width modulation (PWM) comparator (that also provides current-limit control), and a totem-pole output stage designed to source or sink high-peak current. The output stage, suitable for driving N-channel MOSFETs, is low when it is in the off state.

Major differences between members of these series are the UVLO thresholds and maximum duty-cycle ranges. Typical UVLO thresholds of 16 V (on) and 10 V (off) on the TLx842 and TLx844 devices make them ideally suited to off-line applications. The corresponding typical thresholds for the TLx843 and TLx845 devices are 8.4 V (on) and 7.6 V (off). The TLx842 and TLx843 devices can operate to duty cycles approaching 100%. A duty-cycle range of 0 to 50% is obtained by the TLx844 and TLx845 by the addition of an internal toggle flip-flop, which blanks the output off every other clock cycle.

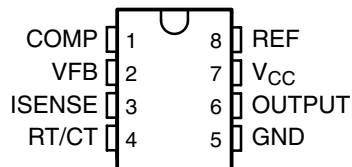
The TL284x-series devices are characterized for operation from –40°C to 85°C. The TL384x devices are characterized for operation from 0°C to 70°C.

**D PACKAGE
(TOP VIEW)**



NC – No internal connection

**D-8 OR P PACKAGE
(TOP VIEW)**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2008, Texas Instruments Incorporated

TL284x, TL384x CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

ORDERING INFORMATION†

T _A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (P) (8 pin)	Tube of 50	TL3842P	TL3842P
			TL3843P	TL3843P
			TL3844P	TL3844P
			TL3845P	TL3845P
	SOIC (D) (8 pin)	Tube of 75	TL3842D-8	TL3842
		Reel of 2500	TL3842DR-8	
		Tube of 75	TL3843D-8	TL3843
		Reel of 2500	TL3843DR-8	
		Tube of 75	TL3844D-8	TL3844
		Reel of 2500	TL3844DR-8	
		Tube of 75	TL3845D-8	TL3845
		Reel of 2500	TL3845DR-8	
	SOIC (D) (14 pin)	Tube of 50	TL3842D	TL3842
		Reel of 2500	TL3842DR	
		Tube of 50	TL3843D	TL3843
		Reel of 2500	TL3843DR	
		Tube of 50	TL3844D	TL3844
		Reel of 2500	TL3844DR	
		Tube of 50	TL3845D	TL3845
		Reel of 2500	TL3845DR	
–40°C to 85°C	PDIP (P) (8 pin)	Tube of 50	TL2842P	TL2842P
			TL2843P	TL2843P
			TL2844P	TL2844P
			TL2845P	TL2845P
	SOIC (D) (8 pin)	Tube of 75	TL2842D-8	TL2842
		Reel of 2500	TL2842DR-8	
		Tube of 75	TL2843D-8	TL2843
		Reel of 2500	TL2843DR-8	
		Tube of 75	TL2844D-8	TL2844
		Reel of 2500	TL2844DR-8	
		Tube of 75	TL2845D-8	TL2845
		Reel of 2500	TL2845DR-8	
	SOIC (D) (14 pin)	Tube of 50	TL2842D	TL2842
		Reel of 2500	TL2842DR	
		Tube of 50	TL2843D	TL2843
		Reel of 2500	TL2843DR	
		Tube of 50	TL2844D	TL2844
		Reel of 2500	TL2844DR	
		Tube of 50	TL2845D	TL2845
		Reel of 2500	TL2845DR	

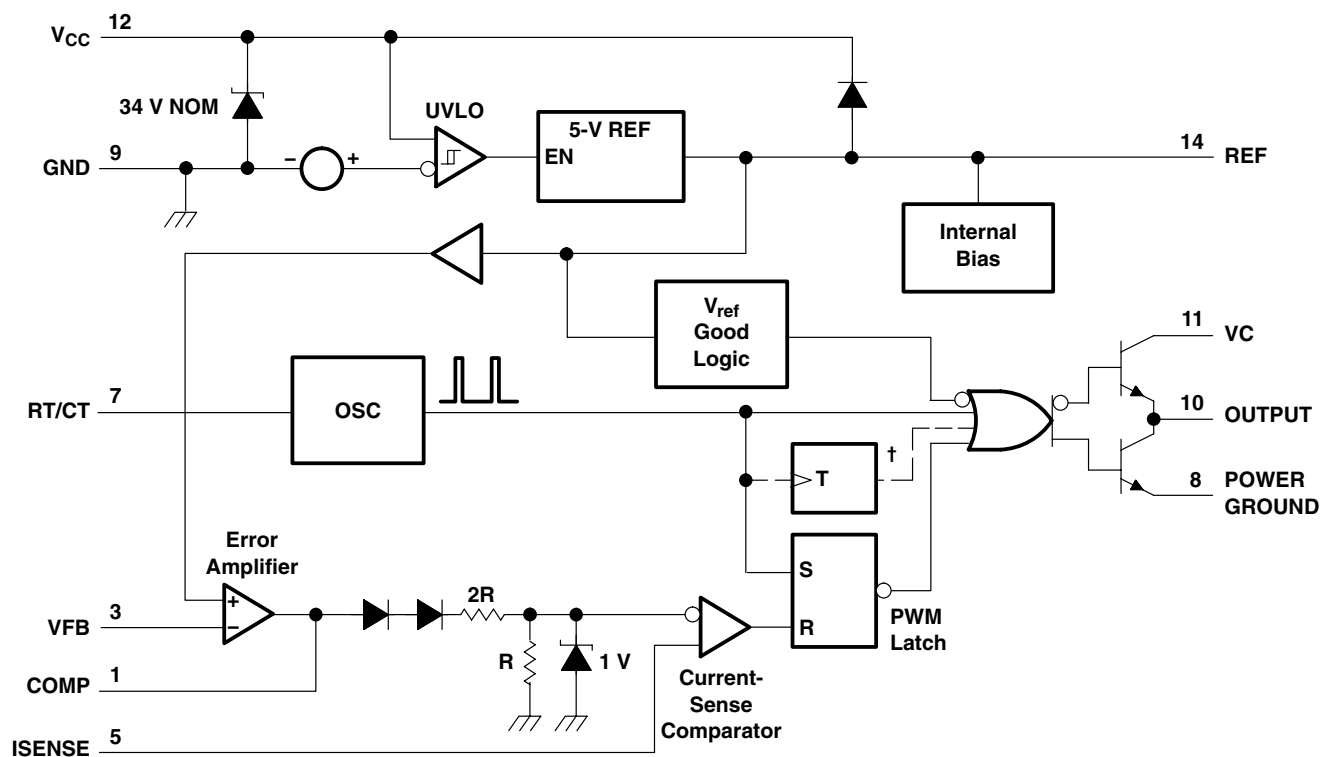
† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

functional block diagram



† The toggle flip-flop is present only in TL2844, TL2845, TL3844, and TL3845.
Pin numbers shown are for the D (14-pin) package.

TL284x, TL384x

CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage (see Note 1) ($I_{CC} < 30$ mA)	Self limiting
Analog input voltage range, V_I (VFB and ISENSE)	–0.3 V to 6.3 V
Output voltage, V_O (OUTPUT)	35 V
Input voltage, V_I , (VC, D package only)	35 V
Supply current, I_{CC}	30 mA
Output current, I_O	±1 A
Error amplifier output sink current	10 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package	86°C/W
D-8 package	97°C/W
P package	85°C/W
Virtual junction temperature, T_J	150°C
Output energy (capacitive load)	5 μ J
Lead temperature, 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to the device GND terminal.

2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC} and $VC^\ddagger$	Supply voltage			30	V
V_I , RT/CT	Input voltage	0		5.5	V
V_I , VFB and ISENSE	Input voltage	0		5.5	V
V_O , OUTPUT	Output voltage	0		30	V
V_O , POWER GROUND [‡]	Output voltage	–0.1		1	V
I_{CC}	Supply current, externally limited			25	mA
I_O	Average output current			200	mA
$I_{O(\text{ref})}$	Reference output current			–20	mA
f_{osc}	Oscillator frequency		100	500	kHz
T_A	Operating free-air temperature	TL284x	–40	85	°C
		TL384x	0	70	

[‡] These recommended voltages for VC and POWER GROUND apply only to the D package.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TL284x, TL384x CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15\text{ V}$ (see Note 4), $R_T = 10\text{ k}\Omega$, $C_T = 3.3\text{ nF}$ (unless otherwise specified)

reference section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Output voltage	$I_O = 1\text{ mA}$, $T_A = 25^\circ\text{C}$	4.95	5	5.05	4.9	5	5.1	V
Line regulation	$V_{CC} = 12\text{ V to }25\text{ V}$	6		20	6		20	mV
Load regulation	$I_O = 1\text{ mA to }20\text{ mA}$	6		25	6		25	mV
Temperature coefficient of output voltage		0.2		0.4	0.2		0.4	mV/°C
Output voltage with worst-case variation	$V_{CC} = 12\text{ V to }25\text{ V}$, $I_O = 1\text{ mA to }20\text{ mA}$	4.9		5.1	4.82		5.18	V
Output noise voltage	$f = 10\text{ Hz to }10\text{ kHz}$, $T_A = 25^\circ\text{C}$	50			50			μV
Output-voltage long-term drift	After 1000 h at $T_A = 25^\circ\text{C}$	5		25	5		25	mV
Short-circuit output current		-30	-100	-180	-30	-100	-180	mA

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.

oscillator section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Oscillator frequency (see Note 5)	$T_A = 25^\circ\text{C}$	47	52	57	47	52	57	kHz
Frequency change with supply voltage	$V_{CC} = 12\text{ V to }25\text{ V}$	2		10	2		10	Hz/kHz
Frequency change with temperature		50			50			Hz/kHz
Peak-to-peak amplitude at RT/CT		1.7			1.7			V

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTES: 4. Adjust V_{CC} above the start threshold before setting it to 15 V.

5. Output frequency equals oscillator frequency for the TLx842 and TLx843. Output frequency is one-half the oscillator frequency for the TLx844 and TLx845.

error-amplifier section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Feedback input voltage	COMP at 2.5 V	2.45	2.50	2.55	2.42	2.50	2.58	V
Input bias current		-0.3		-1	-0.3		-2	μA
Open-loop voltage amplification	$V_O = 2\text{ V to }4\text{ V}$	65	90		65	90		dB
Gain-bandwidth product		0.7	1		0.7	1		MHz
Supply-voltage rejection ratio	$V_{CC} = 12\text{ V to }25\text{ V}$	60	70		60	70		dB
Output sink current	VFB at 2.7 V, COMP at 1.1 V	2	6		2	6		mA
Output source current	VFB at 2.3 V, COMP at 5 V	-0.5	-0.8		-0.5	-0.8		mA
High-level output voltage	VFB at 2.3 V, $R_L = 15\text{ k}\Omega$ to GND	5	6		5	6		V
Low-level output voltage	VFB at 2.7 V, $R_L = 15\text{ k}\Omega$ to GND	0.7	1.1		0.7	1.1		V

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.



TL284x, TL384x

CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15$ V (see Note 4), $R_T = 10$ k Ω , $C_T = 3.3$ nF (unless otherwise specified) (continued)

current-sense section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Voltage amplification	See Notes 6 and 7	2.85	3	3.13	2.85	3	3.15	V/V
Current-sense comparator threshold	COMP at 5 V, See Note 6	0.9	1	1.1	0.9	1	1.1	V
Supply-voltage rejection ratio	$V_{CC} = 12$ V to 25 V, See Note 6	70			70			dB
Input bias current		–2 –10			–2 –10			μ A
Delay time to output		150 300			150 300			ns

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTES: 4. Adjust V_{CC} above the start threshold before setting it to 15 V.

6. These parameters are measured at the trip point of the latch, with VFB at 0 V.

7. Voltage amplification is measured between ISENSE and COMP, with the input changing from 0 V to 0.8 V.

output section

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
High-level output voltage	$I_{OH} = -20$ mA	13	13.5		13	13.5		V
	$I_{OH} = -200$ mA	12	13.5		12	13.5		
Low-level output voltage	$I_{OL} = 20$ mA		0.1	0.4		0.1	0.4	V
	$I_{OL} = 200$ mA		1.5	2.2		1.5	2.2	
Rise time	$C_L = 1$ nF, $T_A = 25^\circ\text{C}$		50	150		50	150	ns
Fall time	$C_L = 1$ nF, $T_A = 25^\circ\text{C}$		50	150		50	150	ns

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.

undervoltage-lockout section

PARAMETER		TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Start threshold voltage	TLx842, TLx844	15	16	17	14.5	16	17.5	V
	TLx843, TLx845	7.8	8.4	9	7.8	8.4	9	
Minimum operating voltage after startup	TLx842, TLx844	9	10	11	8.5	10	11.5	V
	TLx843, TLx845	7	7.6	8.2	7	7.6	8.2	

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.

pulse-width-modulator section

PARAMETER		TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Maximum duty cycle	TLx842, TLx843	95	97	100	95	97	100	%
	TLx844, TLx845	46	48	50	46	48	50	
Minimum duty cycle		0			0			

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.



TL284x, TL384x CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15\text{ V}$ (see Note 4), $R_T = 10\text{ k}\Omega$, $C_T = 3.3\text{ nF}$ (unless otherwise specified) (continued)

supply voltage

PARAMETER	TEST CONDITIONS	TL284x			TL384x			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
Start-up current			0.5	1		0.5	1	mA
Operating supply current	VFB and ISENSE at 0 V		11	17		11	17	mA
Limiting voltage	$I_{CC} = 25\text{ mA}$		34			34		V

† All typical values are at $T_A = 25^\circ\text{C}$.

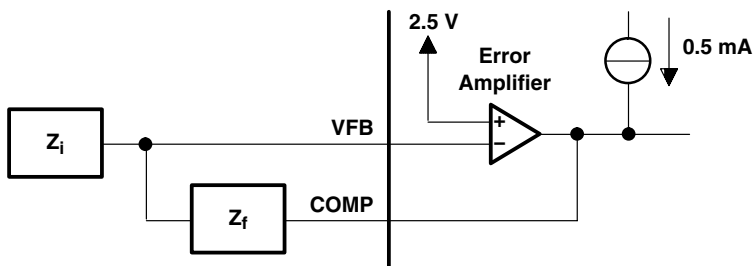
NOTE 4: Adjust V_{CC} above the start threshold before setting it to 15 V.



TL284x, TL384x CURRENT-MODE PWM CONTROLLERS

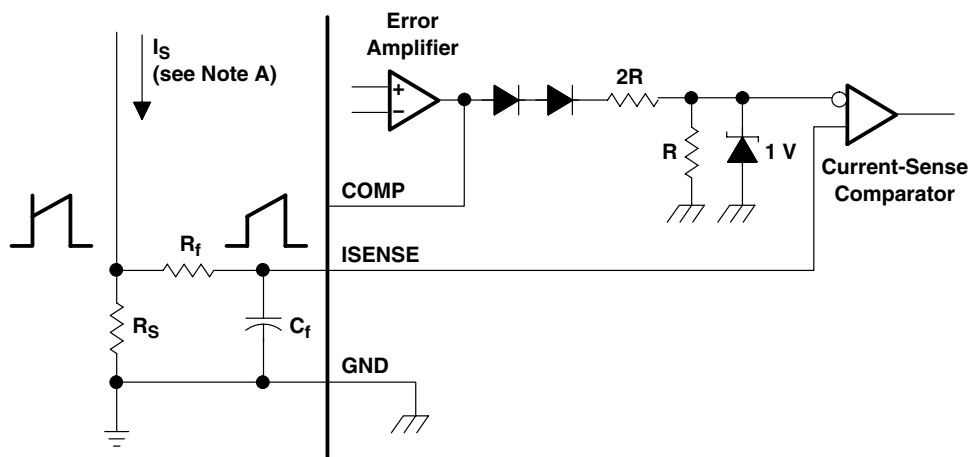
SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

APPLICATION INFORMATION



NOTE A: Error amplifier can source or sink up to 0.5 mA.

Figure 1. Error-Amplifier Configuration

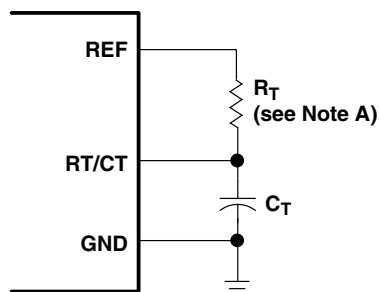


NOTE A: Peak current (I_S) is determined by the formula:

$$I_{S(max)} = \frac{1V}{R_S}$$

A small RC filter formed by resistor R_f and capacitor C_f may be required to suppress switch transients.

Figure 2. Current-Sense Circuit



NOTE A: For $R_T > 5 \text{ k}\Omega$: $f \approx \frac{1.72}{R_T C_T}$

Figure 3. Oscillator Section

APPLICATION INFORMATION

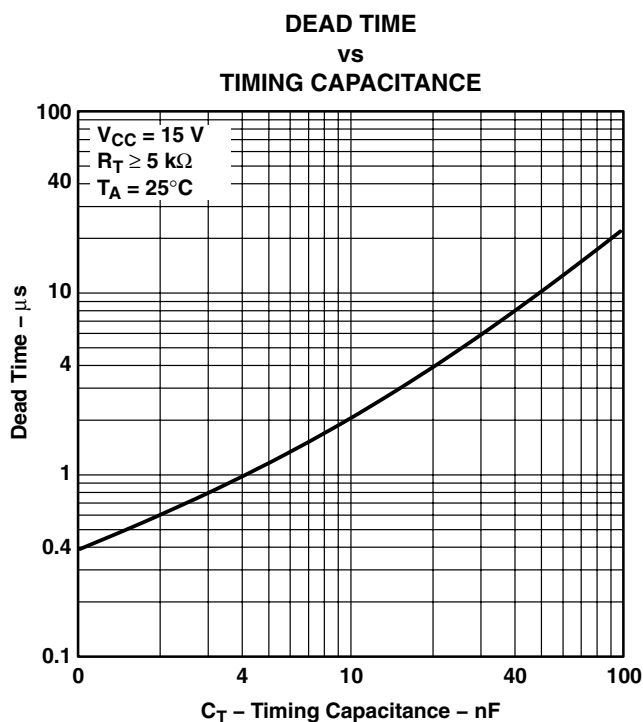


Figure 4

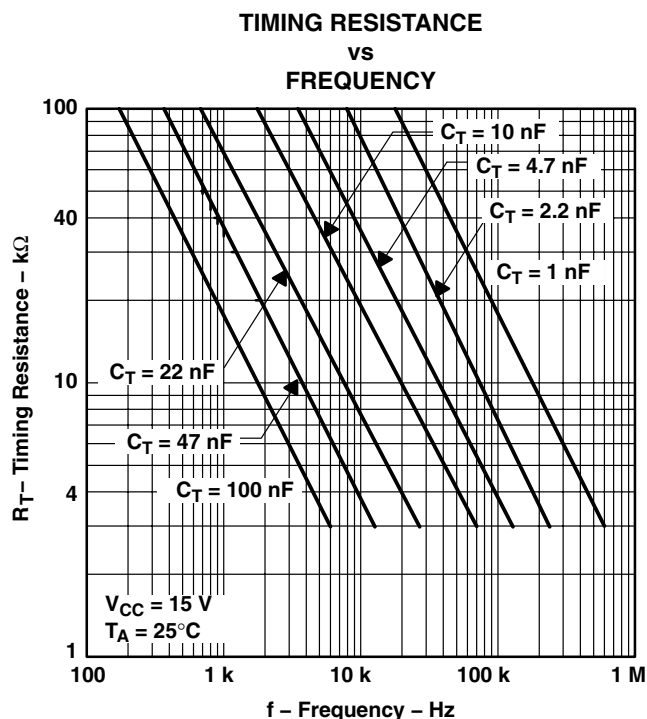


Figure 5

open-loop laboratory test fixture

In the open-loop laboratory test fixture (see Figure 6), high peak currents associated with loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to the GND terminal in a single-point ground. The transistor and 5-k Ω potentiometer sample the oscillator waveform and apply an adjustable ramp to the ISENSE terminal.

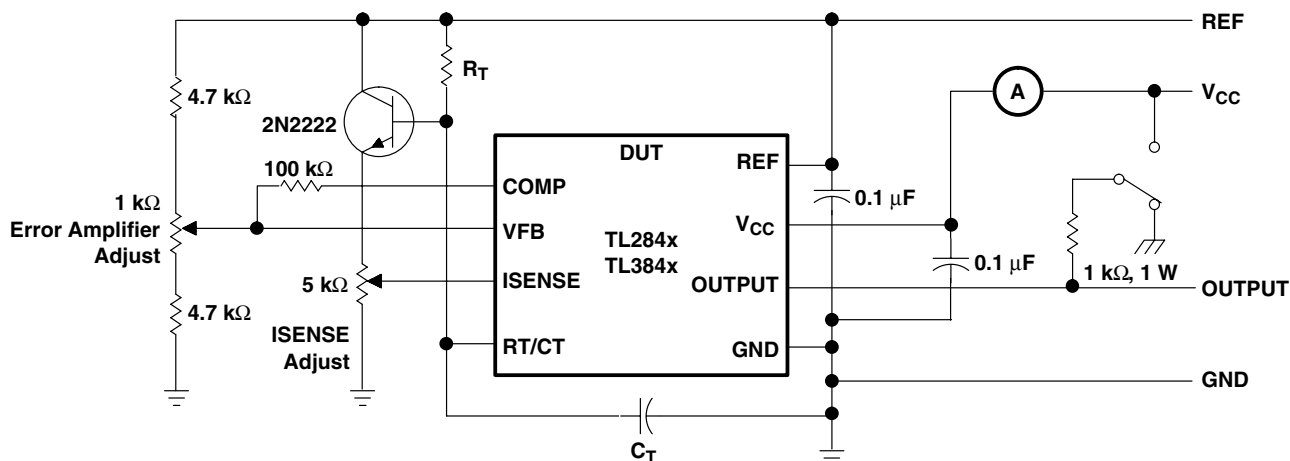


Figure 6. Open-Loop Laboratory Test Fixture

TL284x, TL384x CURRENT-MODE PWM CONTROLLERS

SLVS038G – JANUARY 1989 – REVISED FEBRUARY 2008

APPLICATION INFORMATION

shutdown technique

The PWM controller (see Figure 7) can be shut down by two methods: either raise the voltage at ISENSE above 1 V or pull the COMP terminal below a voltage two diode drops above ground. Either method causes the output of the PWM comparator to be high (refer to block diagram). The PWM latch is reset dominant so that the output remains low until the next clock cycle after the shutdown condition at the COMP or ISENSE terminal is removed. In one example, an externally latched shutdown can be accomplished by adding an SCR that resets by cycling V_{CC} below the lower UVLO threshold. At this point, the reference turns off, allowing the SCR to reset.

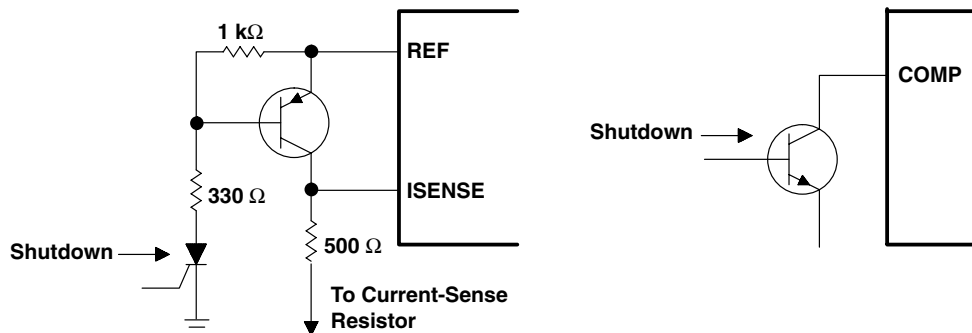


Figure 7. Shutdown Techniques

A fraction of the oscillator ramp can be summed resistively with the current-sense signal to provide slope compensation for converters requiring duty cycles over 50% (see Figure 8). Note that capacitor C forms a filter with R2 to suppress the leading-edge switch spikes.

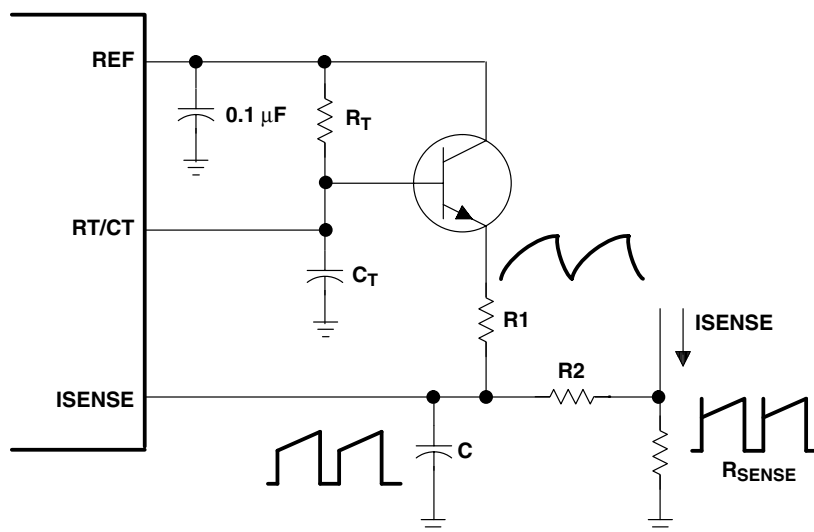


Figure 8. Slope Compensation

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL2842D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TL2842	Samples
TL2842D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TL2842	Samples
TL2842DE4-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TL2842	Samples
TL2842DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TL2842	Samples
TL2842DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TL2842	Samples
TL2842P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2842P	Samples
TL2843D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843DG4-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843DRG4-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2843	Samples
TL2843P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2843P	Samples
TL2844D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844	Samples
TL2844D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844	Samples
TL2844DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL2844DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844	Samples
TL2844DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2844	Samples
TL2844P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2844P	Samples
TL2844PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2844P	Samples
TL2845D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845DG4-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TL2845	Samples
TL2845P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2845P	Samples
TL2845PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TL2845P	Samples
TL3842D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples
TL3842D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples
TL3842DE4-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples
TL3842DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples
TL3842DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples
TL3842DRE4-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 70	TL3842	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL3842P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3842P	Samples
TL3842PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3842P	Samples
TL3843D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843DRG4-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3843	Samples
TL3843P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3843P	Samples
TL3843PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3843P	Samples
TL3844D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844	Samples
TL3844D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844	Samples
TL3844DG4-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844	Samples
TL3844DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844	Samples
TL3844DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3844	Samples
TL3844P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3844P	Samples
TL3844PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3844P	Samples
TL3845D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL3845D-8	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples
TL3845DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples
TL3845DR-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples
TL3845DRE4-8	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples
TL3845DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL3845	Samples
TL3845P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3845P	Samples
TL3845PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL3845P	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

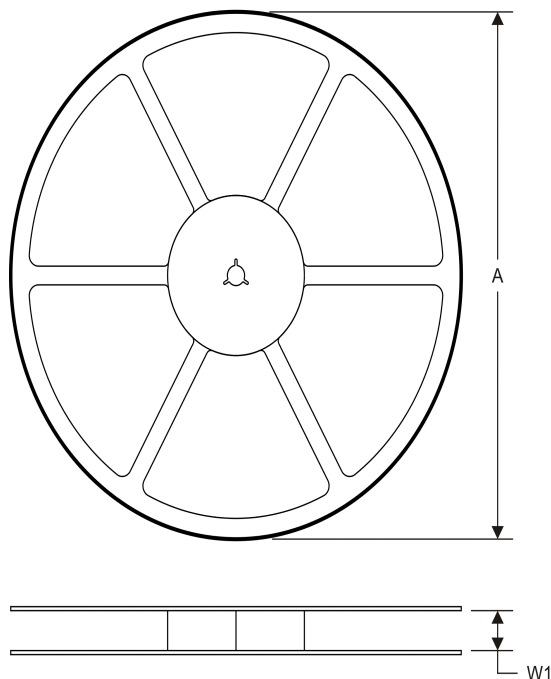
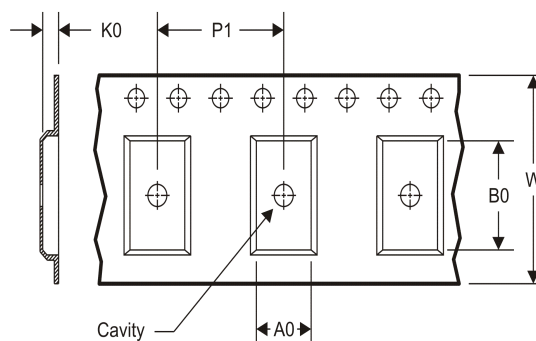
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


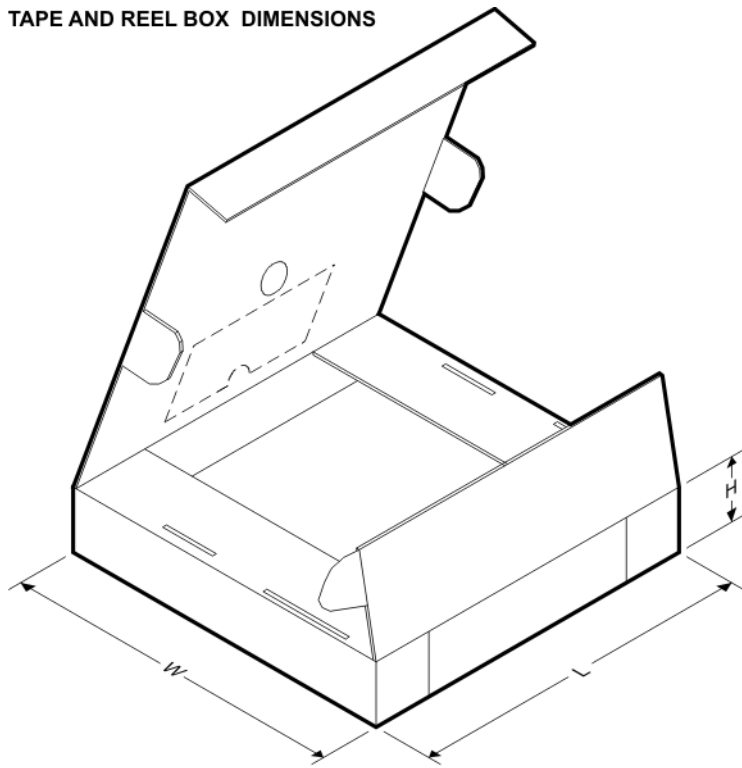
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL2842DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2842DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2843DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2843DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2844DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2844DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2844DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL2845DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL2845DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3842DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3842DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3843DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3843DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3844DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3844DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3844DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3845DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TL3845DR-8	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

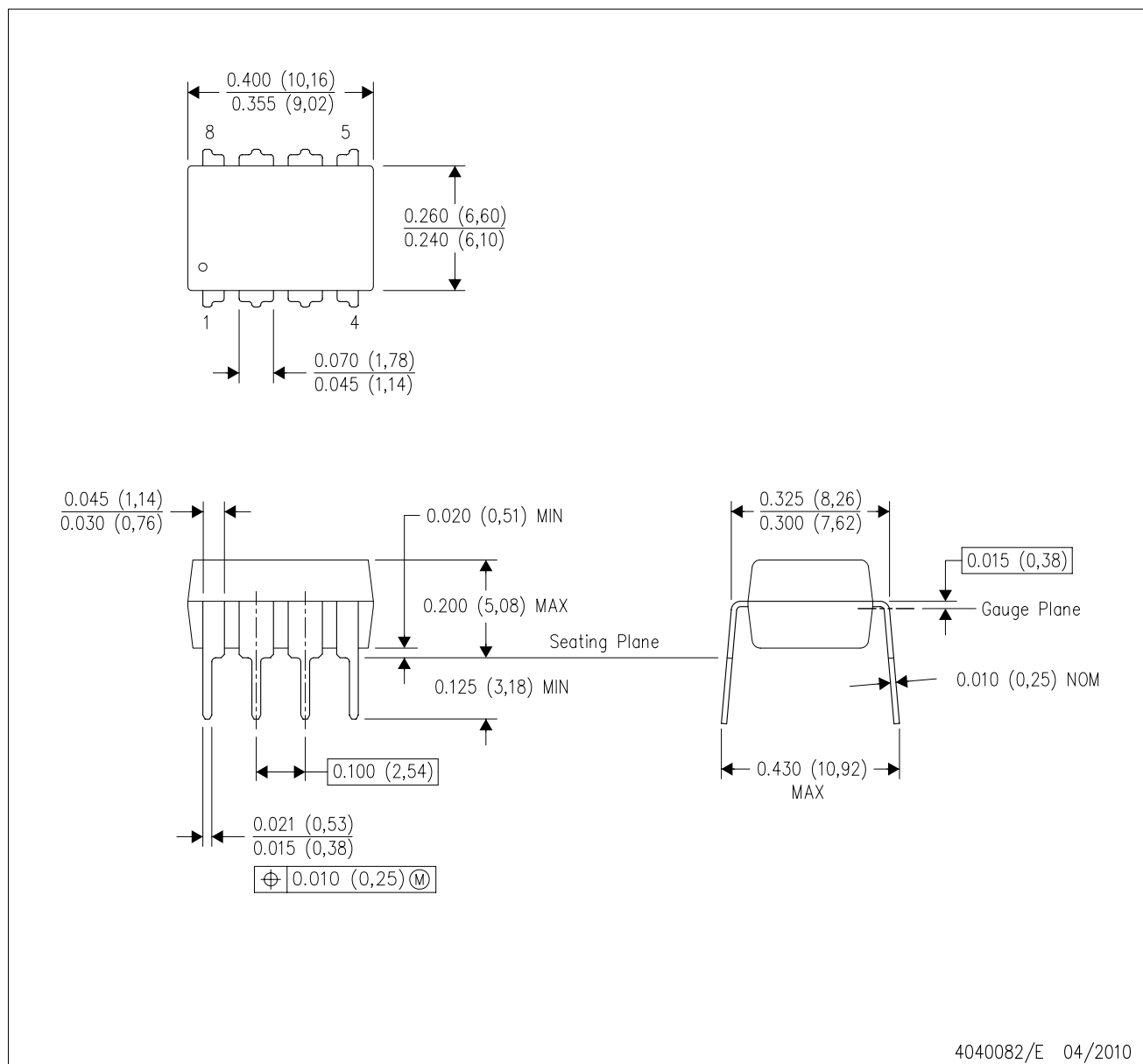


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL2842DR	SOIC	D	14	2500	367.0	367.0	38.0
TL2842DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL2843DR	SOIC	D	14	2500	367.0	367.0	38.0
TL2843DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL2844DR	SOIC	D	14	2500	367.0	367.0	38.0
TL2844DR	SOIC	D	14	2500	333.2	345.9	28.6
TL2844DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL2845DR	SOIC	D	14	2500	367.0	367.0	38.0
TL2845DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL3842DR	SOIC	D	14	2500	367.0	367.0	38.0
TL3842DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL3843DR	SOIC	D	14	2500	367.0	367.0	38.0
TL3843DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL3844DR	SOIC	D	14	2500	367.0	367.0	38.0
TL3844DR	SOIC	D	14	2500	333.2	345.9	28.6
TL3844DR-8	SOIC	D	8	2500	340.5	338.1	20.6
TL3845DR	SOIC	D	14	2500	367.0	367.0	38.0
TL3845DR-8	SOIC	D	8	2500	340.5	338.1	20.6

P (R-PDIP-T8)

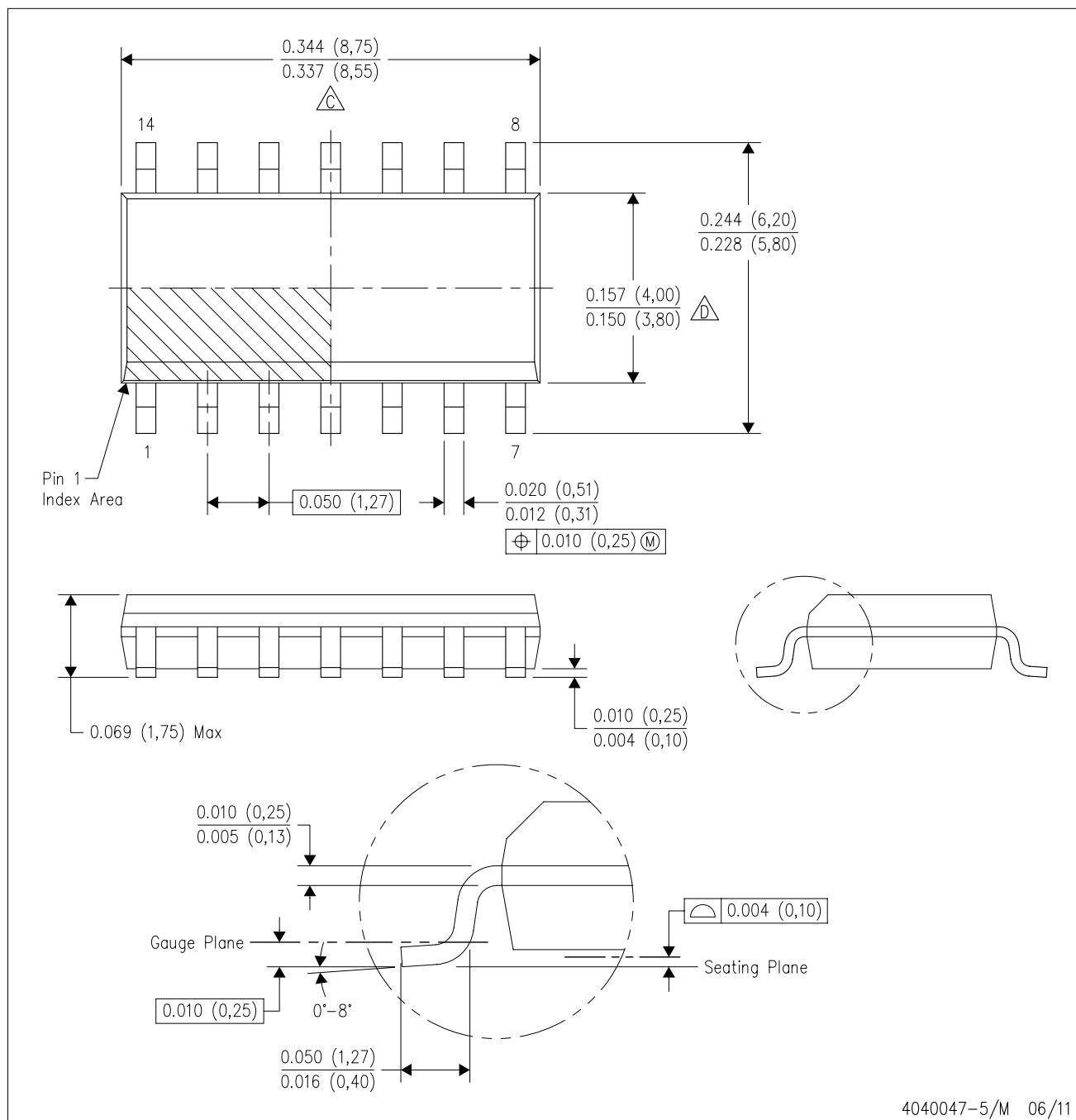
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

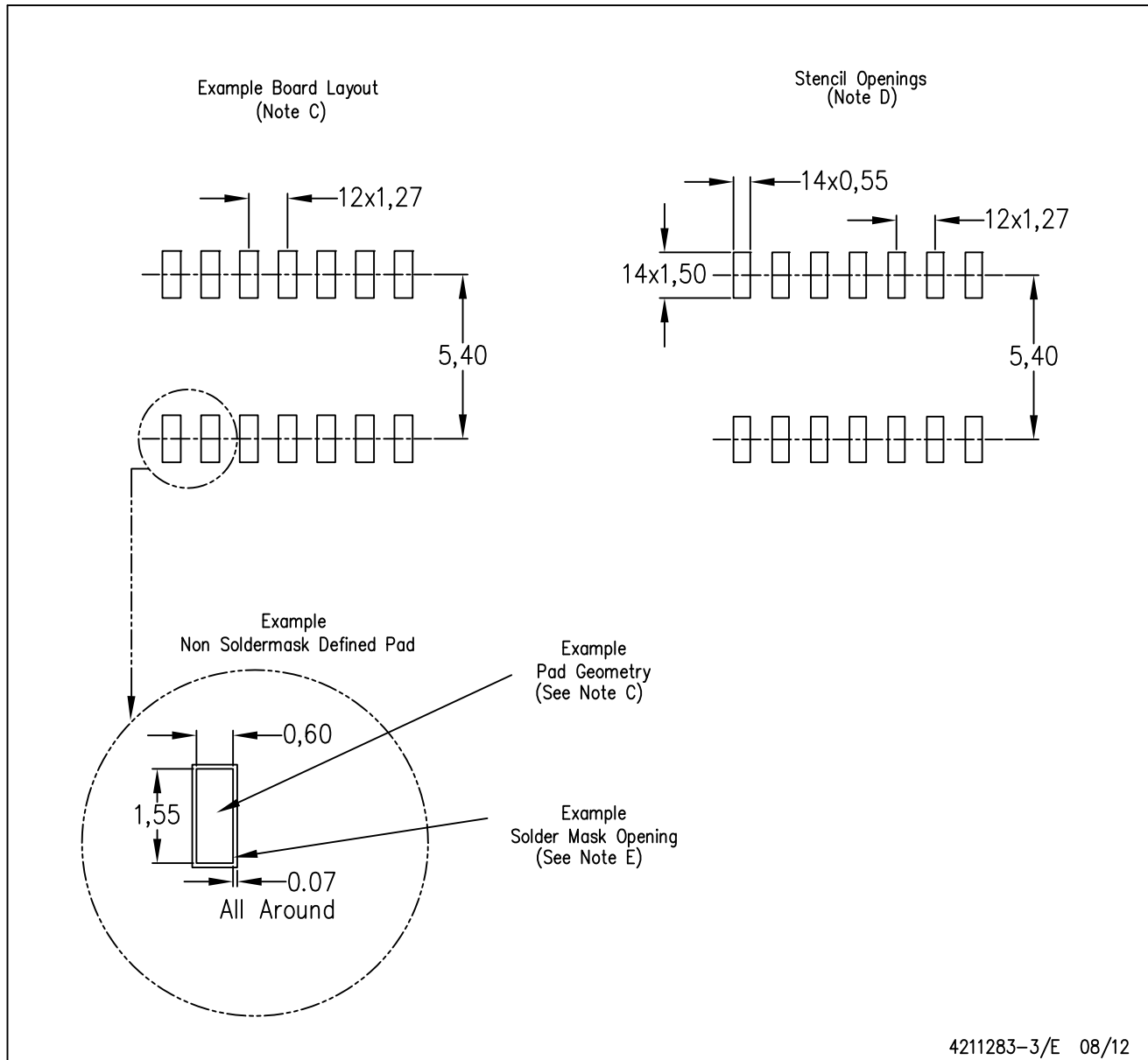


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

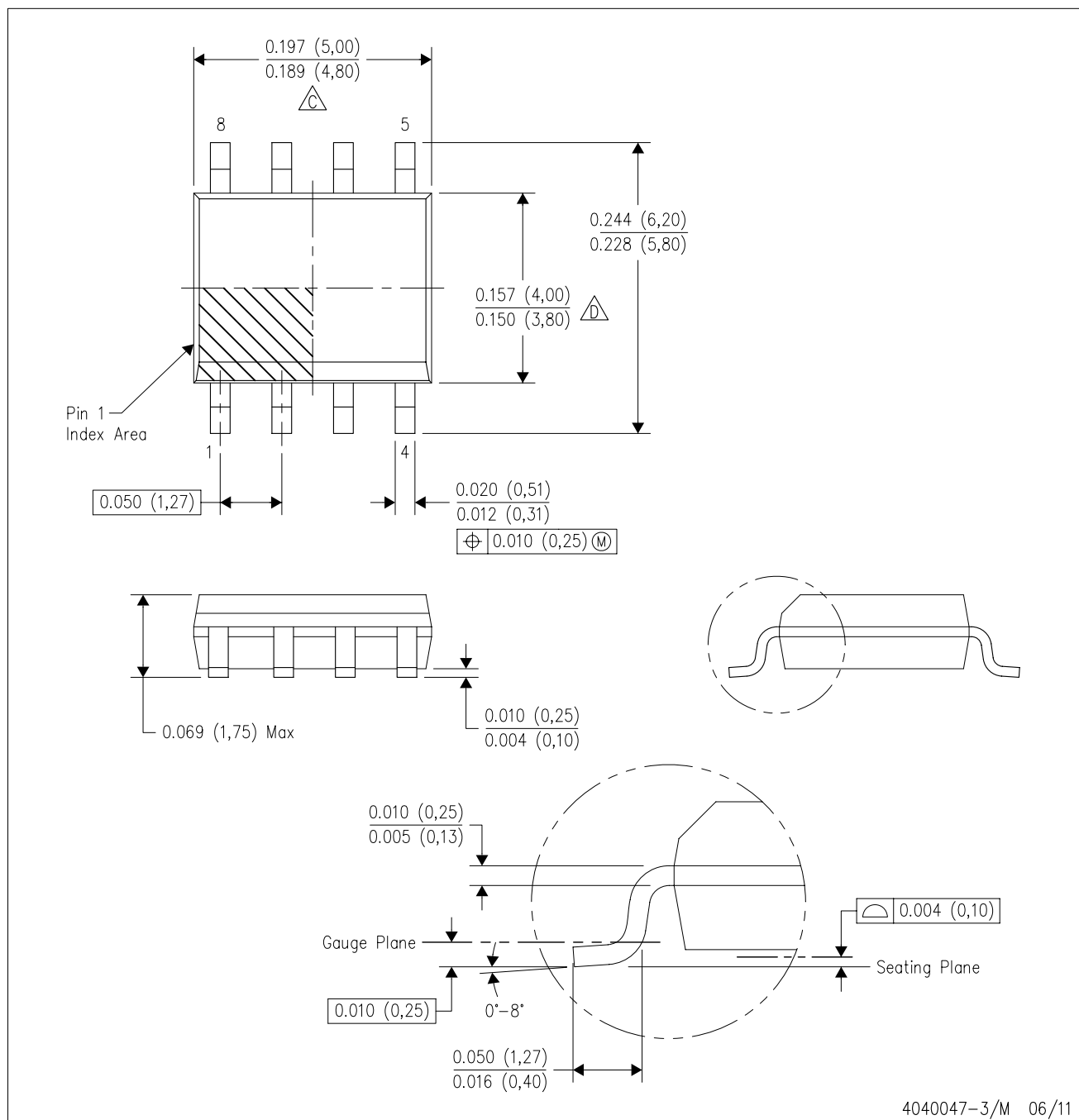
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R-PDSO-G8)

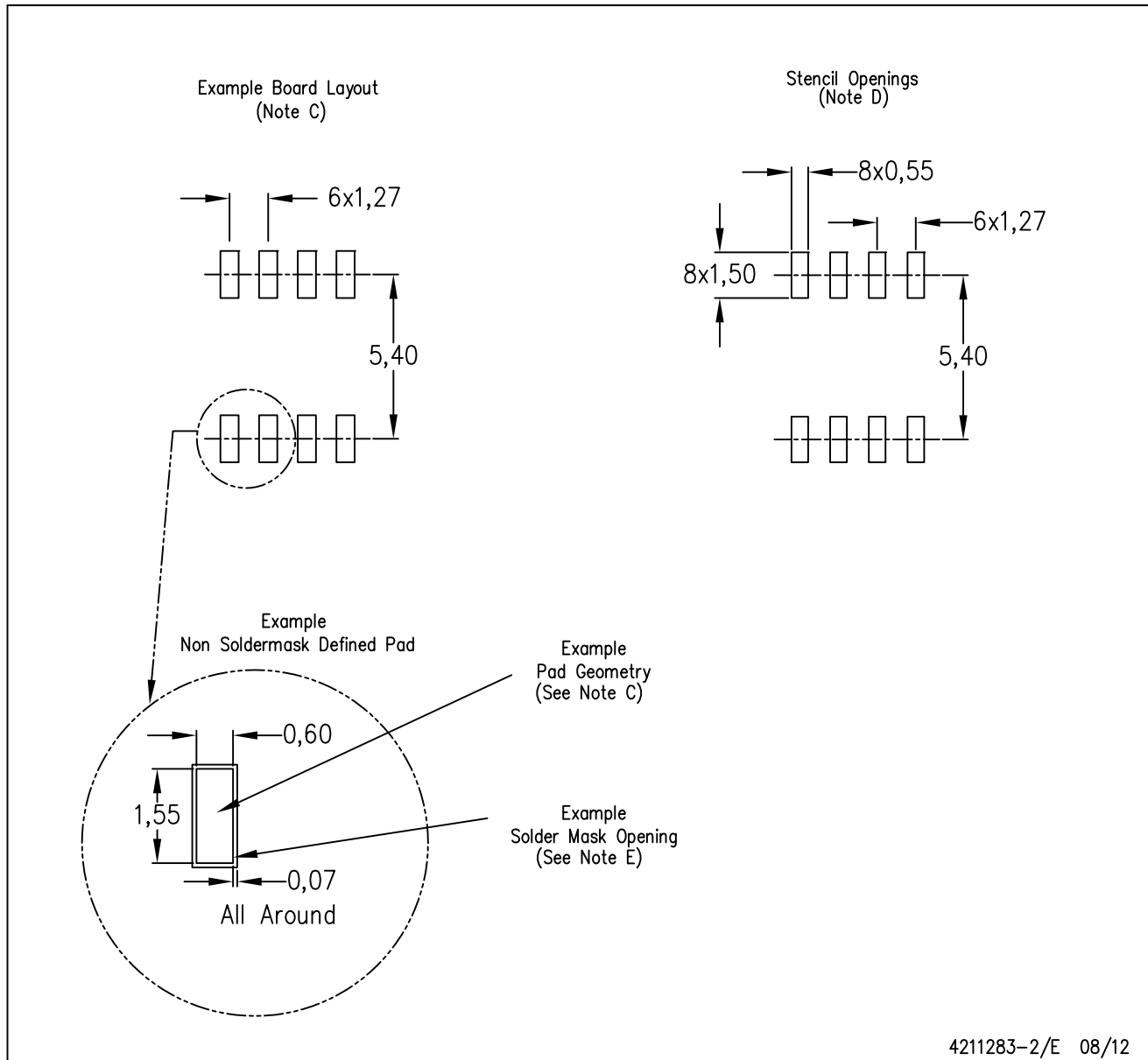
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com